

斜視図
SCALE 5:1

部品構成 MATERIAL

1.ハウジング：液晶ポリマー(LCP)、ガラス充填、ナチュラル、UL94V-0
HOUSING : LIQUID CRYSTAL POLIMER(LCP), GLASS FILLED, NATURAL UL94V-0

2.奇数タ-ミナル：リン青銅
ODD TERMINAL : PHOSPHOR BRONZE
処理：ニッケル下地(1.0μm以上)
コンタクト部：部分金メッキ(0.1μm以上)
テール部：部分金メッキ
ニッケルストライプ(バリア)

FINISH : OVER NICKEL PLATING (1.0 MICROMETER MINIMUM)
CONTACT AREA : SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
SOLDER TAIL AREA : SEPARATED GOLD PLATING NI STRIPE(BARRIER)

3.偶数タ-ミナル：リン青銅
EVEN TERMINAL :PHOSPHOR BRONZE
処理：ニッケル下地(1.0μm以上)
コンタクト部：部分金メッキ(0.1μm以上)
テール部：部分金メッキ
ニッケルストライプ(バリア)

FINISH : OVER NICKEL PLATING (1.0 MICROMETER MINIMUM)
CONTACT AREA : SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
SOLDER TAIL AREA : SEPARATED GOLD PLATING NI STRIPE(BARRIER)

4.アクチュエ-タ：ポリアミド(PA)、ガラス充填、黒色、UL94V-0
ACTUATOR : POLYAMIDE(PA), GLASS FILLED, BLACK, UL94V-0

5.ネイル：リン青銅
NAIL : PHOSPHOR BRONZE
処理：ニッケル下地すずめっき
FINISH : TIN OVER NICKEL PLATING

| | | | | | |
|------|------|------|------|-----------------------------------|----------|
| 15.6 | 14.4 | 15.0 | 17.2 | 502350-5110 | 51 |
| 14.4 | 13.2 | 13.8 | 16.0 | 502350-4710 | 47 |
| 13.8 | 12.6 | 13.2 | 15.4 | 502350-4510 | 45 |
| 12.6 | 11.4 | 12.0 | 14.2 | 502350-4110 | 41 |
| 12.0 | 10.8 | 11.4 | 13.6 | —//— | 39 |
| 11.4 | 10.2 | 10.8 | 13.0 | —//— | 37 |
| 10.2 | 9.0 | 9.6 | 11.8 | 502350-3310 | 33 |
| 9.6 | 8.4 | 9.0 | 11.2 | 502350-3110 | 31 |
| 7.2 | 6.0 | 6.6 | 8.8 | 502350-2310 | 23 |
| 6.0 | 4.8 | 5.4 | 7.6 | 502350-1910 | 19 |
| 4.8 | 3.6 | 4.2 | 6.4 | 502350-1510 | 15 |
| D | C | B | A | EMBOSSED TAPE ORDER NO. オーダー番号 | CIRCUITS |

CONNECTOR SERIES NO. 502350-**19

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | |
|------------------|-------|
| 10 UNDER | ±0.2 |
| 10 OVER 30 UNDER | ±0.25 |
| 30 OVER | ±0.3 |

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

| | | |
|--|--------|-------------------|
| DIMENSION UNITS | SCALE | CURRENT REV DESC: |
| mm | 10:1 | |
| GENERAL TOLERANCES (UNLESS SPECIFIED) | | |
| 4 PLACES | MM | INCH |
| 3 PLACES | ± | ± |
| 2 PLACES | ± | ± |
| 1 PLACE | ± | ± |
| 0 PLACES | ± | ± |
| ANGULAR TOL ± 3.0° | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | |
| THIRD ANGLE PROJECTION | | |
| DRAWING | SERIES | MATERIAL NUMBER |
| A3-SIZE | 502350 | SEE TABLE |
| CUSTOMER GENERAL SHEET NUMBER | | |
| 1 OF 2 | | |

EC NO: 626023
DRWN: AKUMAR19 2019/10/21
CHK'D: GGA 2019/10/22
APPR: GGA 2019/10/22

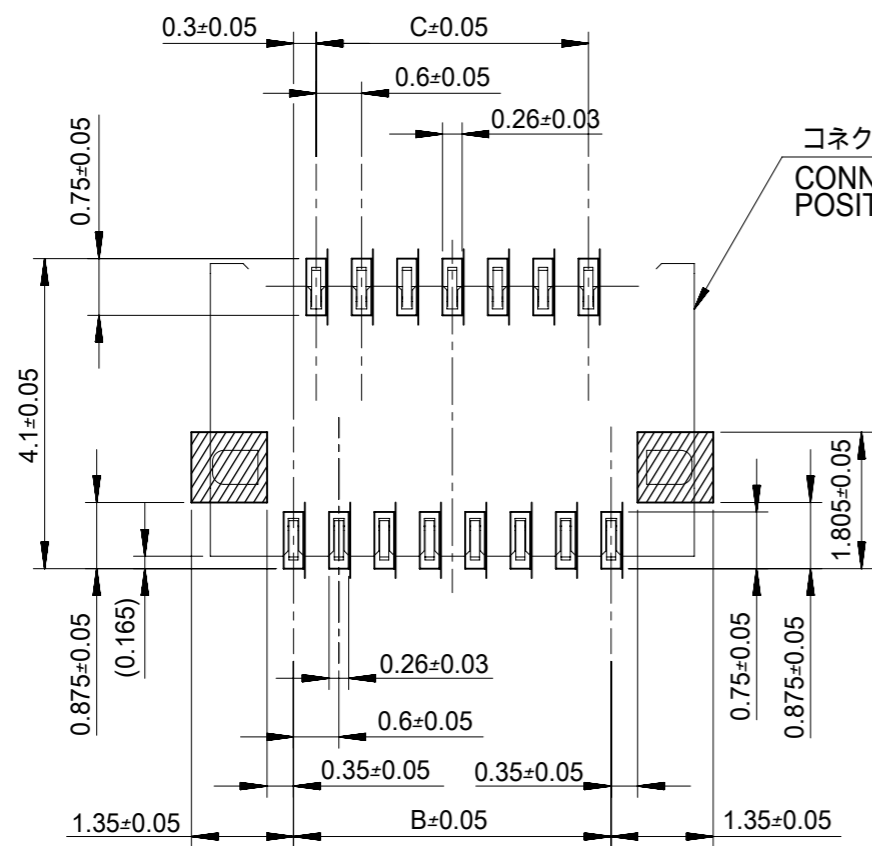
INITIAL REVISION:
DRWN: SHIRATA 2012/03/26
APPR: KMORIKAWA 2012/03/27

molex

0.3 FPC CONN. E/O H=1.1
HOUSING ASSY WITH GUIDE

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER: SD-502350-003
DOC TYPE: PSD
DOC PART: 001
REVISION: B



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN
DIM.(REF.)

| |
|--|
| 推奨メタルマスク厚さ : 0.1mm |
| RECOMMENDED METAL MASK THICKNESS : 0.1mm |
| 推奨開口率 : 100% |
| APERTURE RATE : 100% |

注記
NOTE

- 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板に実装してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE
- FPCについて

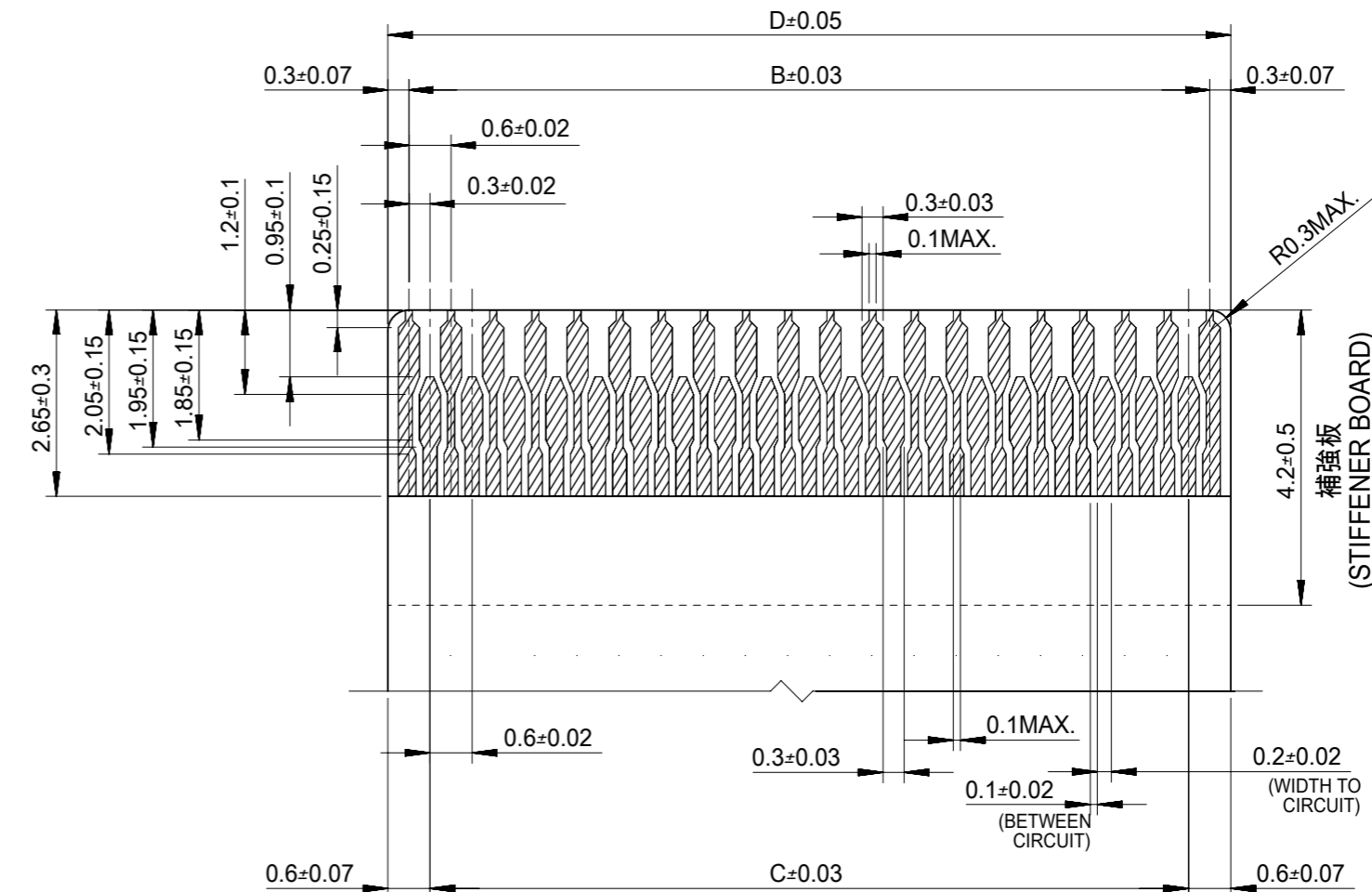
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。
導体部については軟銅箔35μmまたは50μmを推奨致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPECIFICATION:
THICKNESS OF SOFT COPPER FOIL: 35 MICROMETER OR 50 MICROMETER

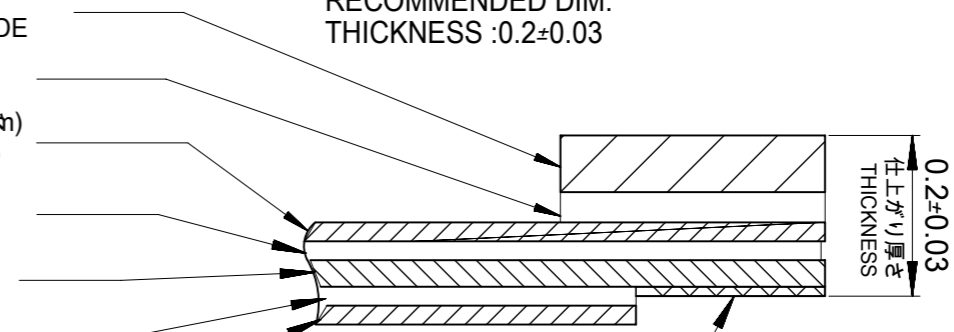
- 平坦度は0.1以下
COPLANARITY TO BE 0.1 MAXIMUM
- 502350-**19限定形状
ONLY USED BY 502350-**19
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03
APPLY FPC
RECOMMENDED DIM.
THICKNESS : 0.2±0.03

補強板 : ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム : ポリイミド(25μm)
BASE FILM: POLYIMIDE(25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部 : 銅箔(35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ : ポリイミド(25μm)
COVER FILM: POLYIMIDE(25μm)



めっき : 金めっき(1μm以上)
下地ニッケル (1-5μm)
PLATING: GOLD(0.1μmMIN.)
NICKEL UNDER (1-5μm)

FPC構成推奨仕様
STRUCTURE OF FPC

| | | | | | |
|---|-------|----------------------------|--|----------------------------|--|
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| GENERAL TOLERANCES (UNLESS SPECIFIED) | | CHK'D: GGA 2019/10/22 | | DOCUMENT NUMBER | |
| 4 PLACES ± | | APPR: GGA 2019/10/22 | | SD-502350-003 | |
| 3 PLACES ± | | INITIAL REVISION: | | DOC TYPE DOC PART REVISION | |
| 2 PLACES ± | | DRWN: SHIRATA 2012/03/26 | | PSD 001 B | |
| 1 PLACE ± | | APPR: KMORIKAWA 2012/03/27 | | MATERIAL NUMBER | |
| 0 PLACES ± | | ANGULAR TOL ± 3.0° | | CUSTOMER | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIRD ANGLE PROJECTION | | SHEET NUMBER | |
| 10 UNDER ±0.2 | | DRAWING | | SEE TABLE | |
| 10 OVER 30 UNDER ±0.25 | | SERIES | | GENERAL | |
| 30 OVER ±0.3 | | A3-SIZE | | 2 OF 2 | |